

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



re Application of
Seigi AOYAMA et al.
Application S/N 09/892,630
Filed: June 28, 2001

: Art Unit: 2827
: Examiner: T. Dinh

For: LEAD-FREE SOLDER, AND CONNECTION LEAD AND ELECTRICAL
COMPONENT USING SAID LEAD-FREE SOLDER

REQUEST FOR RECONSIDERATION

Honorable Assistant Commissioner
for Patents
Washington, DC 20231

Sir:

This Request for Reconsideration is filed concurrently with the filing of a Request for Continued Examination and further to the Amendment filed on March 19, 2003, and the Advisory Action issued on May 6, 2003.